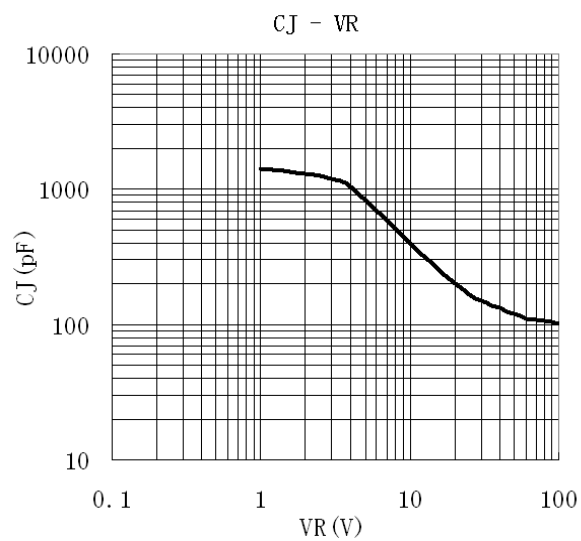
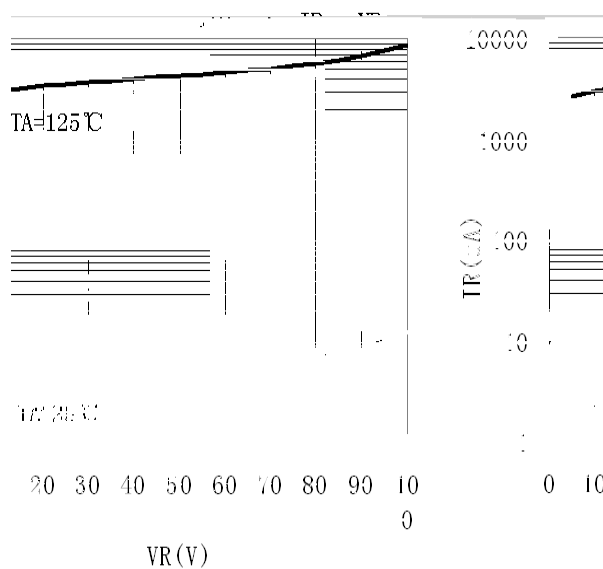
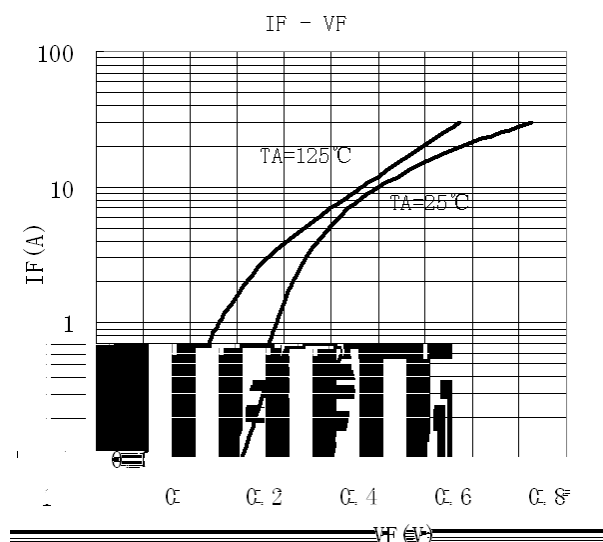
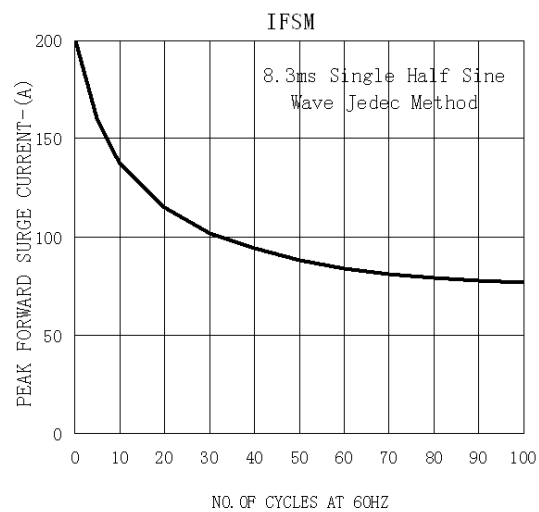
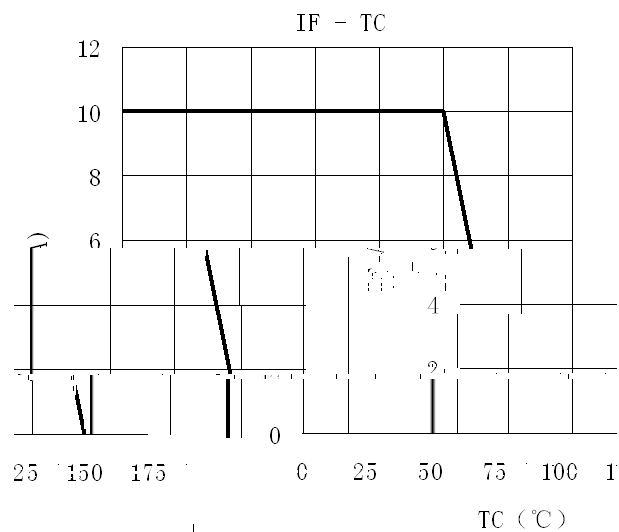


		θ	$/W$
	$1/W$		
Junction and Storage Temperature Range	$T_j \quad T_{stg}$	-55 +150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{(BR)}$	$I_R=1mA(T_a=25^{\circ}C)$			V	
Forward Voltage	V_F	$I_F=2A(T_a=25^{\circ}C)$		0.41	0.45	V
		$I_F=10A(T_a=25^{\circ}C)$	0.58	0.65	V	
		$I_F=2A(T_a=125^{\circ}C)$	0.31	0.40	V	
		$I_F=10A(T_a=125^{\circ}C)$	0.55	0.65	V	
Instantaneous Reverse Current	I_R Note 2	$V_R=100V(T_a=125^{\circ}C)$				

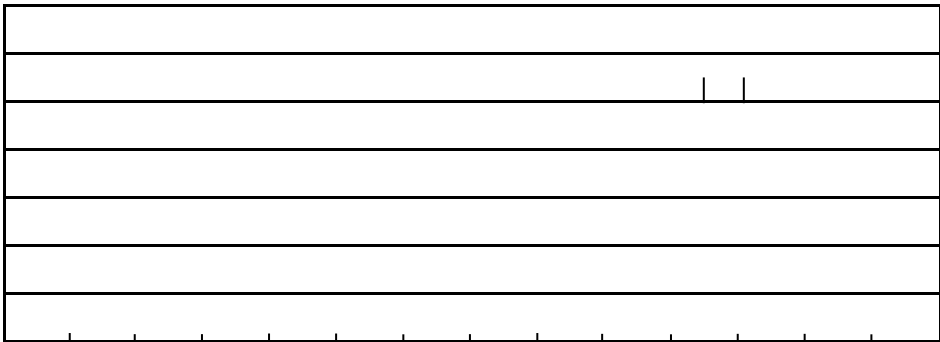
/ Electrical Characteristic Curve



/ Package Dimensions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245 5

5 0.5sec;

2.Peak Temp.:245 5 , Duration:5 0.5sec.
- 3

2 10

/sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-277	5,000	3	15,000	6	90,000	13 ×12	360×360×50	380×335×366

/ Notices